

**IN THE CLAIMS:**

The status of each claim that has been introduced in the above-referenced application is identified in the ensuing listing of the claims. This listing of the claims replaces all previously submitted claims listings.

1-22 (Canceled)

23. (Previously presented) A method for assembling semiconductor devices, comprising:  
providing a first semiconductor device;  
placing discrete conductive elements over portions of the first semiconductor device; and  
setting a back side of a second semiconductor device against at least some of the discrete conductive elements with the back side and the at least some of the discrete conductive elements being electrically isolated from each other; and  
introducing adhesive material between the first semiconductor device and the second semiconductor device.

24. (Previously presented) The method of claim 23, wherein positioning the second semiconductor device comprises positioning the second semiconductor device on the at least some of the discrete conductive elements with the back side and the discrete conductive elements in mutual electrical isolation.

25. (Previously presented) The method of claim 24, further comprising:  
providing a dielectric coating on at least portions of the discrete conductive elements.

26. (Previously presented) The method of claim 25, wherein the providing comprises forming at least one of a dielectric oxide and a dielectric polymer coating on the at least portions of the discrete conductive elements.

27. (Previously presented) The method of claim 24, wherein positioning comprises positioning a dielectric layer on at least portions of the back side thereof.
28. (Canceled)
29. (Previously presented) The method of claim 23, further comprising:  
applying a quantity of adhesive material to at least an active surface of the first semiconductor device.
30. (Previously presented) The method of claim 29, further comprising:  
drawing the second semiconductor device toward the first semiconductor device.
31. (Previously presented) The method of claim 30, wherein drawing is effected by at least one of capillary action of the adhesive material, curing of the adhesive material, application of heat to the adhesive material, and vibration of the adhesive material.
32. (Previously presented) The method of claim 29, wherein applying includes applying the quantity of adhesive material to the back side of the second semiconductor device.
33. (Previously presented) The method of claim 29, wherein applying includes applying the quantity of adhesive material to at least the active surface of the first semiconductor device after positioning the second semiconductor device.
34. (Previously presented) The method of claim 33, further comprising:  
drawing the second semiconductor device toward the first semiconductor device.
35. (Previously presented) The method of claim 34, wherein drawing is effected during curing of the adhesive material.

36. (Withdrawn) The method of claim 29, wherein applying is effected before the positioning the second semiconductor device.

37. (Withdrawn) The method of claim 36, further comprising:  
biasing at least one of the first and second semiconductor devices toward the other of the first and second semiconductor devices.

38. (Withdrawn) The method of claim 37, further comprising:  
controlling the biasing.

39. (Withdrawn) The method of claim 38, wherein controlling the biasing comprises  
controlling biasing force to a level insufficient to deform, kink, bend, or collapse the discrete conductive elements.

40. (Previously presented) The method of claim 23, further comprising:  
securing the first semiconductor device and a substrate to one another.

41. (Previously presented) The method of claim 40, wherein placing discrete  
conductive elements comprises securing the discrete conductive elements to contact areas of the substrate and bond pads of the first semiconductor device.

42. (Previously presented) The method of claim 41, wherein securing comprises  
electrically connecting bond pads of the second semiconductor device to corresponding contact areas of the substrate.

43. (Previously presented) The method of claim 42, further comprising:  
encapsulating at least a portion of at least one of the substrate, the first semiconductor device,  
and the second semiconductor device.

44. (Previously presented) The method of claim 42, further comprising:  
forming external conductive elements on the substrate in electrical communication with the  
corresponding contact areas.

45. (Currently amended) A method for assembling semiconductor devices in a  
stacked arrangement with the stacked arrangement having a height substantially equal to  
combined thicknesses of each of the semiconductor devices and distances discrete conductive  
elements associated therewith protrude above the each of the semiconductor devices, comprising:  
providing electrically coupling a first semiconductor device with to bond pads of discrete  
conductive elements, with portions of the discrete conductive elements protruding from  
an active surface thereof of the first semiconductor device; and  
setting a back side of a second semiconductor device against at least some discrete conductive  
elements of the discrete conductive elements without adhesive material present over the  
active surface of the first semiconductor device, such that the second semiconductor  
device is entirely supported by the at least some discrete conductive elements.

46. (Previously presented) The method of claim 45, wherein positioning comprises  
positioning the second semiconductor device on the at least some of the discrete conductive  
elements with a back side of the second semiconductor device electrically isolated from the  
discrete conductive elements.

47. (Previously presented) The method of claim 46, further comprising:  
providing a dielectric coating on at least portions of the at least some of the discrete conductive  
elements.

48. (Previously presented) The method of claim 46, wherein positioning comprises  
positioning a second semiconductor device that includes a dielectric coating on at least portions  
of the back side thereof.

49. (Previously presented) The method of claim 45, further comprising:  
applying a quantity of adhesive material at least to the active surface of the first semiconductor device.

50. (Previously presented) The method of claim 49, further comprising:  
drawing the second semiconductor device toward the first semiconductor device.

51. (Previously presented) The method of claim 50, wherein drawing is effected by at least one of capillary action of the adhesive material, curing of the adhesive material, application of heat to the adhesive material, and vibration of the adhesive material.

52. (Withdrawn) The method of claim 49, wherein applying is effected before positioning the second semiconductor device.

53. (Previously presented) The method of claim 49, wherein applying is effected after positioning the second semiconductor device.

54. (Previously presented) The method of claim 53, further comprising:  
drawing the second semiconductor device toward the first semiconductor device.

55. (Previously presented) The method of claim 54, wherein drawing is effected during curing of the adhesive material.

56. (Previously presented) The method of claim 49, further comprising:  
biasing at least one of the first and second semiconductor devices toward the other of the first and second semiconductor devices.

57. (Previously presented) The method of claim 56, further comprising:  
controlling the biasing.

58. (Previously presented) The method of claim 57, wherein controlling the biasing comprises controlling biasing force to a level insufficient to deform, kink, bend, or collapse the discrete conductive elements.

59. (Previously presented) The method of claim 45, further comprising:  
positioning the first semiconductor device relative to a substrate.

60. (Previously presented) The method of claim 59, further comprising:  
connecting the discrete conductive elements to corresponding contact areas of the substrate.

61. (Previously presented) The method of claim 59, further comprising:  
establishing electrical communication between bond pads of the second semiconductor device  
and corresponding contact areas of the substrate.

62. (Previously presented) The method of claim 61, wherein establishing  
communication comprises:  
placing additional discrete conductive elements between each of the bond pads and a  
corresponding contact area of the corresponding contact areas.

63. (Previously presented) The method of claim 46, further comprising:  
providing at least one external connective element in communication with at least one bond pad  
of each of the first and second semiconductor devices.

64. (Previously presented) The method of claim 63, further comprising:  
encapsulating at least portions of the first and second semiconductor devices.

65-69 (Canceled)

70. (New) A method for assembling semiconductor devices, comprising:  
providing a first semiconductor device;  
securing the first semiconductor device to a substrate with a first adhesive material;  
placing discrete conductive elements over portions of the first semiconductor device; and  
setting a back side of a second semiconductor device against at least some of the discrete  
conductive elements with the back side and the at least some of the discrete conductive  
elements being electrically isolated from each other; and  
introducing a second adhesive material between the first semiconductor device and the second  
semiconductor device.